

IN THE CLAIMS:

Please cancel claims 1 and 6-11, without prejudice.

Please add newly drafted Claim 15.

1. (Cancelled)
2. (Amended) ~~The A~~ manufacturing method for the gas discharge panel ~~of Claim 1,~~
that has a first substrate on which a protective layer is formed and a second
substrate on which phosphor layers are formed, the manufacturing method comprising an
alignment step for arranging the first substrate and the second substrate at predetermined
locations, while opposing the first substrate and the second substrate,
wherein the alignment step is conducted under a reduced pressure and,
where in the first substrate is p laced under a reduced pressure and heated in a first
reduced pressure chamber and/or the second substrate is placed under a reduced pressure and
heated in a second reduced pressure chamber, prior to the alignment step in which the first and
the second substrates are aligned under a reduced pressure in a third reduced pressure chamber.
3. (Original) The manufacturing method for the gas discharge panel of Claim 2,
wherein, after the protective layer is formed on the first substrate, the first
substrate is subjected to a first substrate baking step in which the first substrate is placed under
the reduced pressure and heated in the first reduced pressure chamber.
4. (Amended) The manufacturing method for the gas discharge panel of ~~Claims 2~~
~~and 3~~ Claim 2,

wherein the second substrate is formed by a phosphor layers forming step, a phosphor layers baking step, a seal member applying step, and a seal member pre-baking step, and

the second substrate is placed under the reduced pressure and heated in the second reduced pressure chamber part way through the seal member pre-baking step.

5. (Original) The manufacturing method for the gas discharge panel of Claim 4, wherein the first and second reduced pressure chambers are each reduced to a pressure of 1,333Pa or less.

6. - 11. (Cancelled)

12. (Amended) The gas discharge panel manufactured by the manufacturing method of ~~Claim 2 or 7~~ Claim 2,

wherein a water vapor partial pressure in the internal space of the panel is 100Pa or less.

13. (Original) A manufacturing apparatus for a gas discharge panel having a first substrate carrying mechanism, a second substrate carrying mechanism, and an alignment mechanism,

wherein each mechanism is provided in different hermetically sealed chambers, which each include at least one of a gas supplying mechanism and a gas exhausting mechanism.

14. (Original) The manufacturing apparatus for the gas discharge panel of Claim 13, wherein connecting units are provided between the chamber including the first substrate carrying mechanism and the chamber including the alignment mechanism and between the

chamber including the second substrate carrying mechanism and the chamber including the alignment mechanism, and

each connecting unit has at least one of a gas supplying mechanism and a gas exhausting mechanism in it.

15. (New) The manufacturing method for the gas discharge panel of Claim 3,

wherein the second substrate is formed by a phosphor layers forming step, a phosphor layers baking step, a seal member applying step, and a seal member pre-baking step, and

the second substrate is placed under the reduced pressure and heated in the second reduced pressure chamber part way through the seal member pre-baking step.